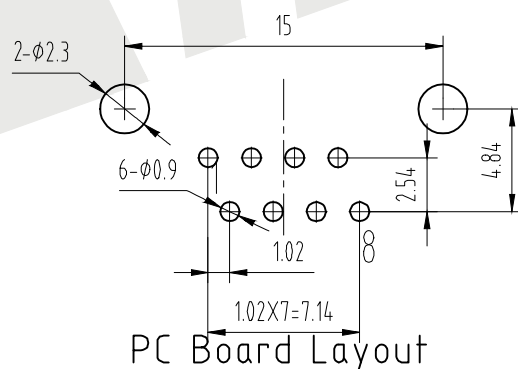
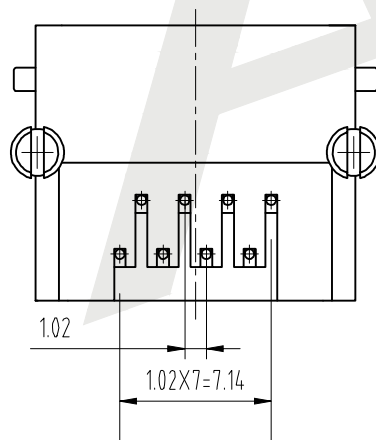
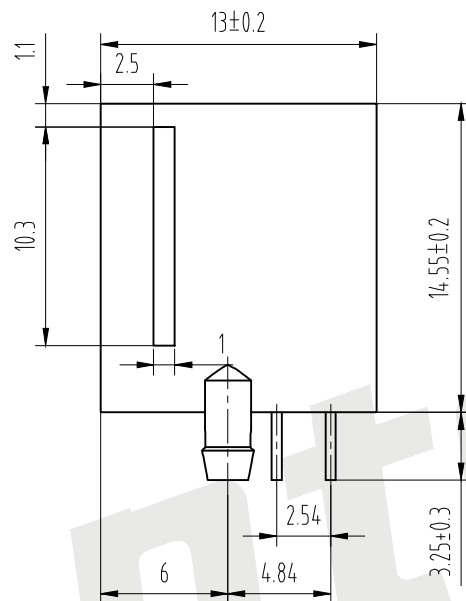
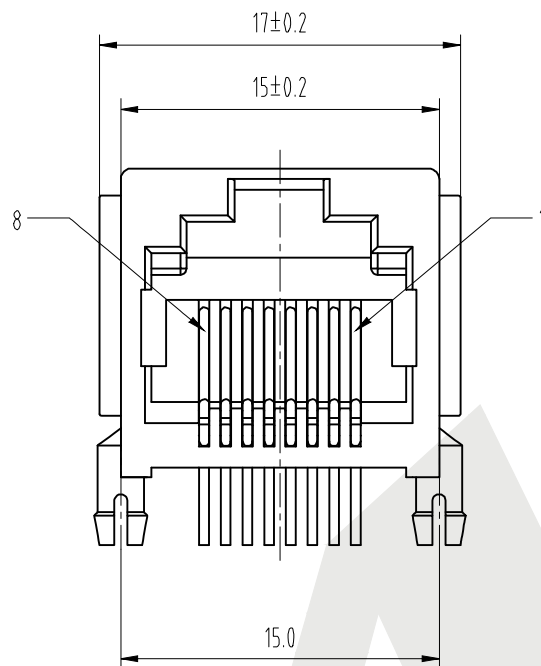


HSF



PC Board Layout  
Component Side Shown

NOTES:

MATERIAL:

1. HOUSING MATERIAL: GLASS FILLED POYESTER UL94V-0.
2. CONTACT MATERIAL: PHOSPHOR BRONZE  $t=0.3\text{mm}$
3. PLATING: SELECTING GOLD PLATING  $1\mu\sim 50\mu$  OVER NICKEL IN CONTACT AREA.  $150\mu$  TIN PLATIN. OVER NICKEL IN SOLDER AREA
4. SHIELD: 0.2mm THICKNESS COPPER WITH NICKEL PLATE

ELECTRICAL

1. VOLTAGE RATING: 125VAC RMS
2. CURRENT RATING: 1.5AMP
3. CONTACT RESISTANCE: 30MILLIOHMS MAX
4. INSULATION RESISTANCE 500MEGOHMS MIN @500V DC
5. DIELECTRIC WITHSTANDING RESISTANCE : 1000V AC RMS 50Hz. 1MIN

MECHANICAL

1. DURRABILITY: 750 CYCLES MIN
2. PCB RETENTTON PRB-SOLDER: 1 LB MIN

REVRONMENTAL

1. STORAGE:  $-40^{\circ}\text{C}$  TO  $85^{\circ}\text{C}$
2. OPERATION:  $0^{\circ}\text{C}$  TO  $70^{\circ}\text{C}$

Order code:

ATRJ5521 - 8P - 8C - X - A - A - A  
① ② ③ ④ ⑤ ⑥ ⑦

① SERIES NO:

- ② NUMBER OF POSITIONS (8P, 6P, 4P)
- ③ NUMBER OF CONTACTS (8C, 6C, 4C)
- ④ Contact Plating

- G0: Gold flash
- G1: 3U" Gold
- G2: 5U" Gold
- G3: 10U" Gold
- G4: 15U" Gold
- G5: 30U" Gold
- SN: Tin

- ⑥ Ports
- A: 1X1P
  - B: 1X2P
  - C: 1X4P
  - D: 1X5P
  - E: 1X6P
  - F: 1X8P

⑤ Shield

- A: W/O Shield
- B: Half Shield
- C: Shield W/Eml
- D: Shield W/O Eml

⑦ With Panel or not

- A: With panel
- B: Without panel

Unless Otherwise specified tolerance  
X.  $\pm 0.35$  X.XX:  $\pm 0.20$   
X.X:  $\pm 0.25$  X.XXX:  $\pm 0.15$

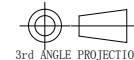
**Antenk**® ANTENK ELECTRONICS CO., LTD  
Http://www.antenk.com  
E-mail:sales@antenk.com

SCALE: As Shown UNIT: mm  
DRAW Wu Feng Rong DATE 06/09/2019  
CHECK BobYang DATE 06/09/2019

TITLE: RJ45 JACK side entry, 1X1P, Full Plastic with panel

DRAWING NO: ATRJ5521-8P8C-X-A-A-A

PRODUCT NO: ATRJ5521-8P8C-X-A-A-A



REV	DESCRIPTION	DATE
1		
2		
3		
4		
5		